# RoHS **1 CG/CG2 Series**

ittelfuse

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# **Agency Approvals**

AGENCY	AGENCY FILE NUMBER		
<b>R</b>	E128662		
R	E320116		

# 2 Electrode GDT Graphical Symbol



# Description

Littelfuse highly reliable CG/CG2 Series GDTs provide a high degree of surge protection in a small size ideal for board level circuit protection.

GDTs function as switches which dissipate a minimum amount of energy and therefore handle currents that far surpass other types of transient voltage protection. Their gas-filled, rugged ceramic metal construction make them well suited to adverse environments.

The CG/CG2 series comes in a variety of forms including surface mount, core, straight and shaped leads, to serve a variety of mounting methods.

The CG Series (75-110V) is ideal for protection of test and communication equipment and other devices in which low voltage limits and extremely low arc voltages are required.

The CG2 Series (145V-1000V) is ideal for protecting equipment where higher voltage limits and holdover voltages are necessary.

NOTE REGARDING 'SN' PRODUCTS: CG2 SN products were designed for surge protection applications for which the radioactive isotope used in standard CG/CG2 devices is not desired. Since the end of 2007 all CG/CG2 products are non-radioactive. See Part Numbering System diagram for additional ordering information.

# Features

Rugged Ceramic-Metal construction

• Low Capacitance (<1.5pf)

- Available in surface mount, and a variety of lead options options
- Meets REA PE-80
- Applications
- Communication lines and equipment
- CATV equipment
- Test equipment
- Data lines

- Power supplies
- Instrumentation circuits
- Medical electronics
- ADSL equipment
- Telecom SLIC protection



## **Electrical Characteristics**

	Device Specifications (at 25°C)						L	ife Rating	s					
Part		Breakd in Volts @100V/s	s	Impulse Break- down in Volts (@100V/µs)	Impulse Break- down In Volts (@1 Kv/µsec)	Insulation Resistance	Capaci- tance (@1MHz)	Arc Voltage (on state Voltage) @1Amp Min	Surge Life (@500A 10/1000µs)	Nominal Impulse Discharge Current (8/20µs)	Nominal AC Discharge Current (10x1sec @50-60Hz)	AC Dischage Current (9 cycle @50Hz)	DC Holdover Voltage <sup>2</sup>	Max Impulse Discharge Current (1 Application @ 10/350µs)
Number	MIN	TYP	MAX	MAX		MIN	MAX	TYP					TYP	
CG75	60	75	90	400	650									
CG90	72	90	108	400	600	10 <sup>10</sup> Ω							52 V	4kA
CG90 SN	72	90	108	400	600	(at 50V)	: 50V)							
CG110	88	110	132	450	600									
CG2145	116	145	174	500	600								80 V	
CG2145 SN	120	145	174	500	600									
CG2230	195	230	265	600	700									
CG2230 SN	184	230	276	600	700									
CG2250	213	250	288	625	725					10				
CG2250 SN	200	250	300	625	725				400	10 shots (@20kA) <sup>3</sup>	20 A	100 A		
CG2300	255	300	345	700	800		1.5 pf	15 V	400 shots					
CG2300 SN	240	300	360	700	800	10 <sup>10</sup> Ω								2.5kA
CG2350	297	350	403	750	900	(at 100V)								2.5KA
CG2350 SN	280	350	420	750	900								135 V	
CG2420	357	420	483	800	1000									
CG2470	400	470	540	850	1200									
CG2470 SN	376	470	564	850	1200									
CG2600	510	600	690	1000	1400									
CG2600 SN	480	600	720	1000	1400									
CG28001	680	800	920	1200	1500					10 shots	10 A			
CG210001	850	1000	1150	1500	1600					(@10kA)	IUA	65 A		

NOTES:

1. Tested to UL1449 Third Edition

2. Reference REA PE-80, 0.2A. Tested to ITU-T Rec K.12 and REA PE 80 < 150 mSec.

3. Leaded devices = 5x[5(+) or 5(-)] applications 20kA 8/20µSec. (75 to 600 volt devices.)

MS and Core devices = 10x[5(+) and 5(-)] applications 10kA 8/20µS (800 to 1000 volt devices.)

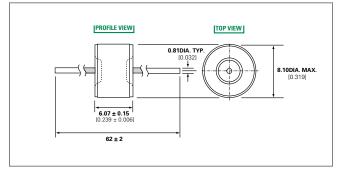
# **Product Characteristics**

Materials	LS, Axial: Device: Nickel Plated 2–5 Microns Lead Wires: Tin Plated 17.5 ± 12.5 Microns Construction: Ceramic Insulator Core: Device: Tin Plated 17.5 ± 12.5 Microns. Construction: Ceramic Insulator MS: Device: Dull Tin Plated 7–9 Microns Construction: Ceramic Insulator
Product Marking	LF Logo, Voltage and date code; Black in positive print

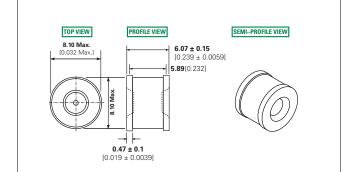
Glow to arc transition current	< 0.5Amps		
Glow Voltage	60-160 Volts		
Storage and Operational Temperature	-40 to +90		
Maximum Follow On Current <sup>1</sup>	230 Volts r.m.s, 200 Amps. (800V and 1000V devices tested to UL1449 3rd edition)		

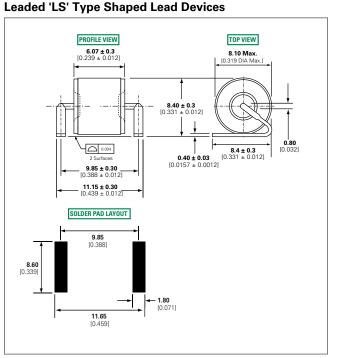
# **Device Dimensions**

#### Leaded 'L' Type Straight Axial Devices

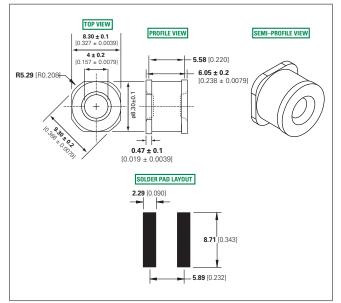


#### **Core Devices**



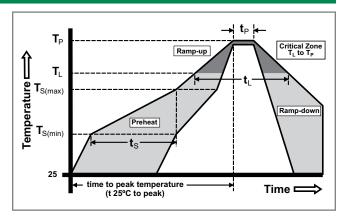


#### 'MS' Type Devices

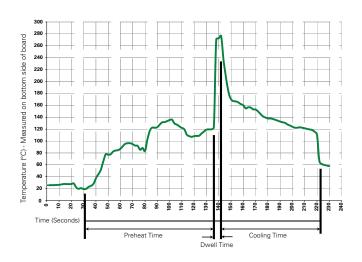


# Soldering Parameters - Reflow Soldering (Surface Mount Devices)

Reflow Co	ndition	Pb – Free assembly		
	-Temperature Min (T <sub>s(min)</sub> )	150°C		
Pre Heat	-Temperature Max (T <sub>s(max)</sub> )	200°C		
	-Time (Min to Max) (t <sub>s</sub> )	60 – 180 secs		
Average ra (T <sub>L</sub> ) to pea	amp up rate (LiquidusTemp k	3°C/second max		
$T_{S(max)}$ to $T_{L}$	- Ramp-up Rate	5°C/second max		
Reflow	-Temperature $(T_L)$ (Liquidus)	217°C		
	-Temperature (t <sub>L</sub> )	60 – 150 seconds		
PeakTemp	erature (T <sub>P</sub> )	260 <sup>+0/-5</sup> °C		
Time with Temperatu	in 5°C of actual peak ıre (t <sub>p</sub> )	10 – 30 seconds		
Ramp-dov	vn Rate	6°C/second max		
Time 25°C	to peakTemperature (T <sub>P</sub> )	8 minutes Max.		
Do not exc	ceed	260°C		



#### Soldering Parameters - Wave Soldering (Thru-Hole Devices)



#### **Recommended Process Parameters:**

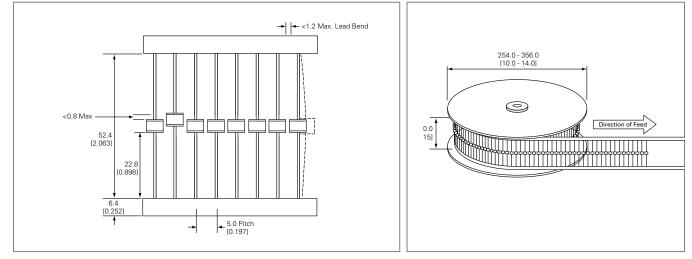
Wave Parameter	Lead-Free Recommendation		
Preheat: (Depends on Flux Activation Temperature)	(Typical Industry Recommendation)		
Temperature Minimum:	100° C		
Temperature Maximum:	150° C		
Preheat Time:	60-180 seconds		
Solder Pot Temperature:	280° C Maximum		
Solder Dwell Time:	2-5 seconds		

# **Soldering Parameters - Hand Soldering**

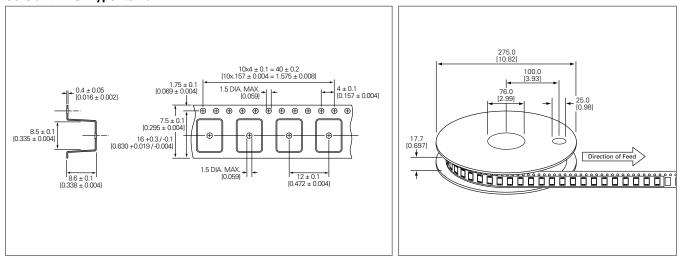
Solder Iron Temperature: 350° C +/- 5°C Heating Time: 5 seconds max.

# **Packaging Dimensions**

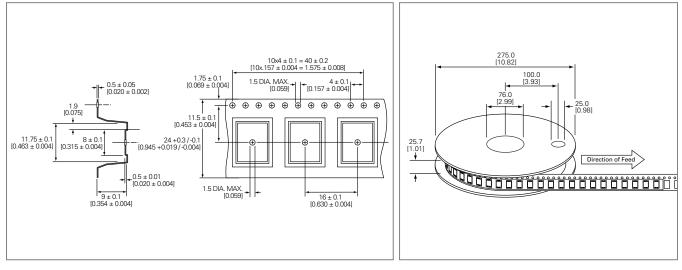
## For 'L' Type Axial Lead Items



# Core and 'MS' Type Items



# For 'LS' Type Shaped Lead Items





# Part Numbering System and Ordering Information

